



30V DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} max	I _D max T _A = +25°C		
00)/	$22m\Omega$ @ $V_{GS} = 10V$	6.7A		
30V	$30m\Omega$ @ $V_{GS} = 4.5V$	5.2A		

Description and Applications

This MOSFET has been designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

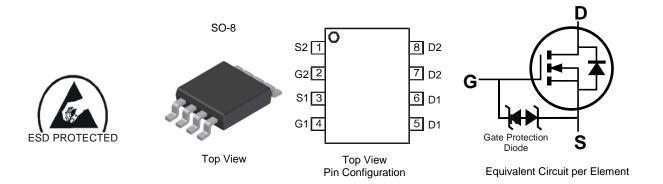
- Backlighting
- Power Management Functions
- DC-DC Converters

Features

- Low On-Resistance
- 100% UIS (Avalanche) Rated
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 ³
- Weight: 0.074 grams (Approximate)



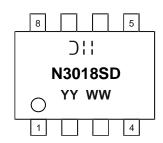
Ordering Information (Note 4)

-			
	Part Number	Case	Packaging
	DMN3018SSD-13	SO-8	2500/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



O∷ = Manufacturer's Marking
N3018SD = Product Type Marking Code
YYWW = Date Code Marking
YY or YY = Year (ex: 16 = 2016)
WW = Week (01 to 53)



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	30	V		
Gate-Source Voltage			V _{GSS}	±20	V
0.5 0.444.577.427		$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	6.7 5.3	А
Continuous Drain Current (Note 5) V _{GS} = 10V	t < 10s	$T_A = +25$ °C $T_A = +70$ °C	I _D	8.7 6.9	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%	I _{DM}	60	Α		
Maximum Body Diode Continuous Current	Is	2.0	Α		
Avalanche Current (Note 6) L = 0.1mH	I _{AR}	19	A		
Repetitive Avalanche Energy (Note 6) L = 0.1mH	E _{AR}	18	mJ		

Thermal Characteristics (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)	P_D	1.5	W	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	ם	83	°C/W
Thermal Resistance, Junction to Ambient (Note 5)	t < 10s	$R_{\theta JA}$	50	°C/W
Thermal Resistance, Junction to Case (Note 5)	$R_{ heta JC}$	14.5	°C/W	
Operating and Storage Temperature Range	$T_{J_{I}}T_{STG}$	-55 to +150	°C	

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

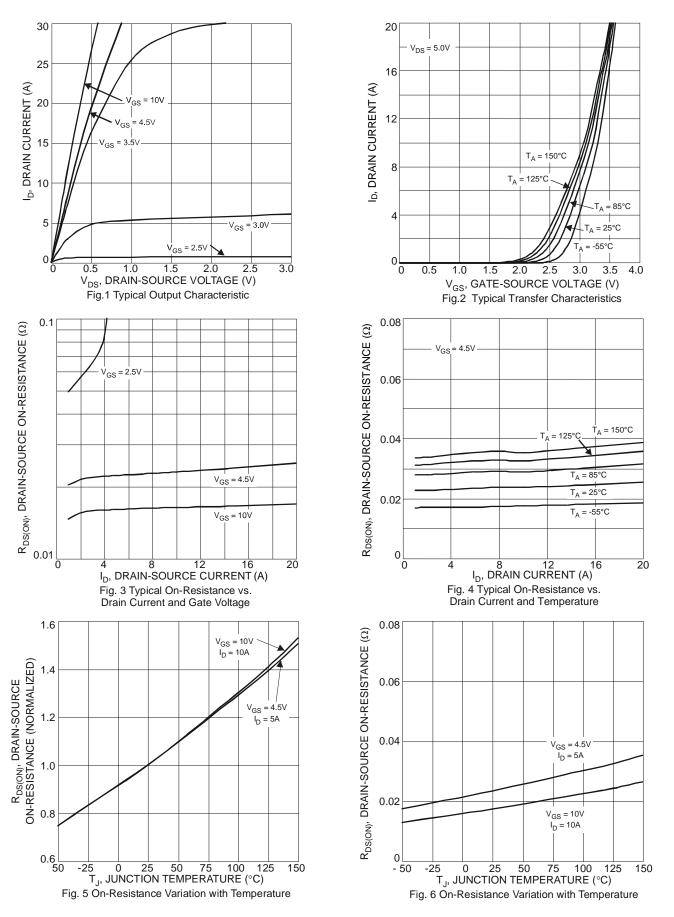
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage		30	_		٧	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}		_	1	μΑ	$V_{DS} = 24V$, $V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(TH)}	1	1.7	2.1	٧	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
Static Drain-Source On-Resistance			16	22	mΩ	$V_{GS} = 10V, I_D = 10A$	
Static Drain-Source On-Nesistance	R _{DS(ON)}		23	30	11122	$V_{GS} = 4.5V, I_D = 6A$	
Forward Transfer Admittance	Y _{fs}	_	8.3	_	S	$V_{DS} = 5V, I_{D} = 6.9A$	
Diode Forward Voltage	V_{SD}	0.5	_	1.2	V	$V_{GS} = 0V, I_{S} = 1A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{iss}	_	697	_		V _{DS} = 15V, V _{GS} = 0V, f = 1.0MHz	
Output Capacitance	Coss	_	97	_	pF		
Reverse Transfer Capacitance	C _{rss}	_	67	_			
Gate Resistance	R _q	_	1.47	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Q_g	_	6.0	_			
Total Gate Charge (V _{GS} = 10V)	Qq	_	13.2	_	C	$V_{GS} = 10V, V_{DS} = 15V,$ $I_{D} = 9A$	
Gate-Source Charge	Q _{gs}	_	2.2	_	nC		
Gate-Drain Charge	Q_{gd}	_	1.8	_			
Turn-On Delay Time	t _{D(ON)}		4.3	_		$V_{DD} = 15V, V_{GS} = 10V,$ $R_{L} = 15\Omega, I_{D} = 1A, R_{G} = 6\Omega$	
Turn-On Rise Time	t _R		4.4	_			
Turn-Off Delay Time	t _{D(OFF)}		20.1	_	ns		
Turn-Off Fall Time	t _F		4.1	_		1	
Reverse Recovery Time	t _{RR}		7.3	_	ns		
Reverse Recovery Charge	Q_{RR}	_	7.9	_	nC	$I_F = 9A$, di/dt = 500A/ μ s	

5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

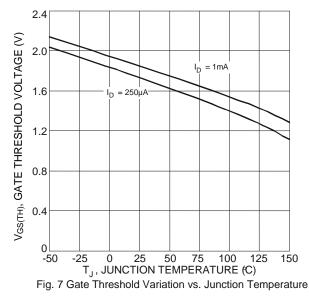
^{6.} I_{AR} and E_{AR} ratings are based on low frequency and duty cycles to keep $T_J = +25^{\circ}C$. 7. Short duration pulse test used to minimize self-heating effect.

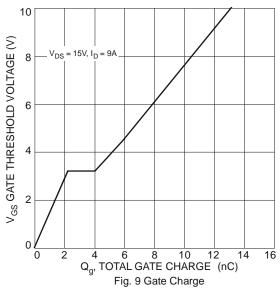
^{8.} Guaranteed by design. Not subject to product testing.

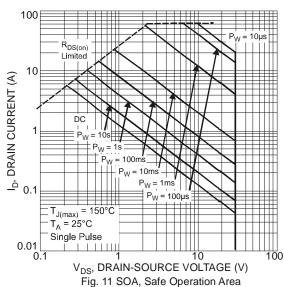


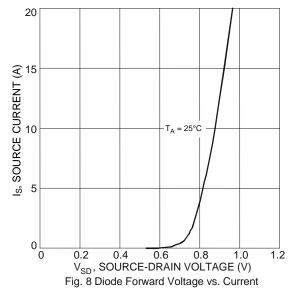


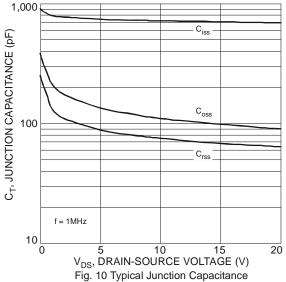




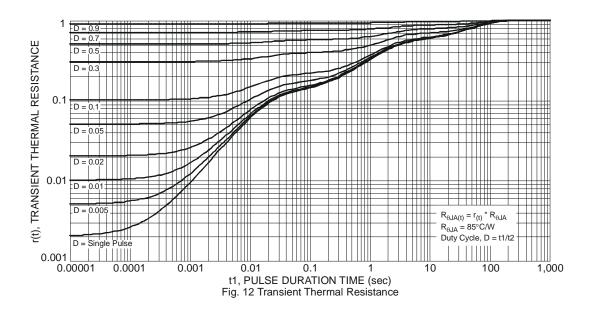






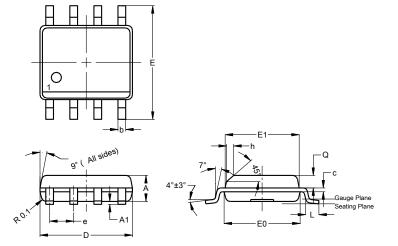






Package Outline Dimensions

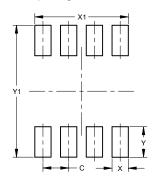
Please see http://www.diodes.com/package-outlines.html for the latest version.



SO-8							
Dim	Min	Max	Тур				
Α	1.40	1.50	1.45				
A1	0.10	0.20	0.15				
b	0.30	0.50	0.40				
С	0.15	0.25	0.20				
D	4.85	4.95	4.90				
Е	5.90	6.10	6.00				
E1	3.80	3.90	3.85				
E0	3.85	3.95	3.90				
е			1.27				
h	-		0.35				
L	0.62	0.82	0.72				
Q	0.60	0.70	0.65				
All Dimensions in mm							

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	1.27
Х	0.802
X1	4.612
Υ	1.505
Y1	6.50



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